FLIP CHIP PACKAGE

Abstract

A flip chip package mainly includes a semiconductor chip disposed in a recessed cavity defined in an upper surface of a substrate by flip chip bonding. The lower surface of the substrate is provided with a reinforcement-containing insulating layer thereby enhancing mechanical strength thereof. The upper surface of the substrate is provided with a plurality of solder pads formed at the periphery of the recessed cavity for making external electrical connections. The substrate includes a plurality of chip contact pads provided on the surface of the reinforcement-containing insulating layer and exposed from the recessed cavity wherein the chip contact pads are electrically connected to the solder pads through a plurality of conductive traces.